

ADOPTION NOTICE

IPC-TM-650, Number 2.6.8, "Thermal Stress, Plated-Through Holes", was adopted on 24 May 2004, for use by the Department of Defense (DoD). Proposed changes by DoD activities must be submitted to the DoD Adopting Activity: Defense Logistics Agency, Defense Supply Center, Columbus, ATTN: DSCC-VAC, P.O. Box 3990, Columbus, OH 43216-5000. Copies of this standard may be purchased from the Association Connecting Electronics Industry, 2215 Sanders Road, Suite 200 South, Northbrook, IL 60062-6135, URL: <http://www.ipc.org>.

Custodians:

Army – CR  
Navy – EC  
Air Force – 11  
DLA – CC

Adopting Activity:  
DLA – CC

(Project 5998–0182)

Reviewer Activity:

Army – AR, AT, EA, MI  
Air Force – 99